

STATEMENT UNDER ARTICLE 19 (1)

By cancelling the claims 7, 8, 9, the applicant makes clear that this application meets the requirements of unity of invention as defined in Rules 13.1 and 13.2.

JP2002226796 discloses a dicing/die bonding sheet adhesively bonded to a semiconductor wafer prior to the dicing of said semiconductor wafer (A), wherein said dicing/die bonding sheet is provided with a base film (2), an UV radiation curable adhesive layer (3) formed on the above mentioned base film, and a silicone (4) based adhesive agent layer formed on the above mentioned UV radiation curable adhesive layer (3) and having an adhesive surface adhesively bonded to the above mentioned semiconductor wafer (A).

However, UV irradiation is necessary in order to reduce the tack properties of the base film with respect to the adhesive agent layer when pieces of a semiconductor wafer are removed from the base film after dicing a semiconductor wafer using the dicing/die bonding sheet disclosed JP2002226796.

The dicing/die bonding sheet of the present invention is characterized by unnecessary such UV irradiation because the base film is not adhesively bonded to the adhesive agent layer (see paragraph 15 of the application).